

Filename: PMP5734 REV\_B\_bom.xls

Date: 09/30/2011

## PMP5734 REV\_B BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C3	0.047uF	Capacitor, Ceramic, 630V, X7R, 20%	1210	C3225X7R2J473M	TDK
1	C4	330pF	Capacitor, Ceramic, 630V, C0G, NP0, ±5%	1206	Std	Std
1	C8	680uF	Capacitor, Aluminum, 13V, 105C, 20%	0.315 inch	EKZM160ESS681MH15D	Nippon Chemi-Con
1	C10	1000pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H102K	TDK
1	C11	470pF	CAP 250VAC CERAMIC Y2/X1	0.236 x 0.315 inch	ECK-NVS471KB	Panasonic
1	C12	10pF	Capacitor, Ceramic, 50V, C0G, 10%	0603	STD	STD
1	C14	47uF	Capacitor, Aluminum, SM, ±20%, 35V,	D Code	EEEFK1V470P	Panasonic
1	C16	1nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C17	1000pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C100	0.047uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
2	C1-2	6.8uF	Capacitor, Aluminum, 400V, 105C, 20%	0.315 inch	400AX680Mxxxxyy8x10.8mm	Rubycon
3	C5-7	22uF	Capacitor, Ceramic, 16V, X7R, 20%	1210	C3225X7R1C226M	TDK
3	C9 C13 C15	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
1	D1	RH06-T	Diode, Bridge, 0.5-A, 600-V	MiniDIP	RH06-T	Diodes
1	D3	US1K	Diode, Rectifier, 1A, 800V	SMA	US1K	Diodes
1	D5	MBR0520L	Diode, Schottky, 0.5A, 20V	SOD-123	MBR0520L	Fairchild
1	D100	20V	Diode, Zener, 20-V, 350-mW	SOT-23	BZX84C20LT1	ON Semi
2	D2 D4	BAS21	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS21	Zetex
1	L1	1mH	Inductor, Power, 0.25A, 3.4 Ohms	0.350 x 0.300 inch	RFB0807-102L	Coilcraft
1	L2	1.2uH	Inductor, SMT, 5.3A, 17milliohm	0.235 x 0.380	DO1813HC-122ML	Coilcraft
1	Q3	Si7812DN	MOSFET, Fast Switching, NChan, 75V, 37milliohm	PWRPAK 1212	Si7812DN	Vishay
1	Q4	MMBT2907	Bipolar, PNP, 60V, 600mA	SOT23	MMBT2907LT1	On Semiconductor
1	Q5	SPD04N80C3	MOSFET, N-ch, 800V, 4-A, 1.3 ohm	DPAK	SPD04N80C3	Infineon
2	Q1-2	MMBT2222A	Bipolar, NPN, 40V, 600mA	SOT23	MMBT2222ALT1	ON Semiconductor
1	R1	2.2	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R2	100	Resistor, Chip, 1/10W, 5%	0805	CRCW0805-xxx-J	Vishay
1	R3	220K	Resistor, Chip, 1/2W, 1%	2010	Std	Vishay
1	R5	4.7	Resistor, Fusible Power, 1W	0.300 X 0.100 inch	NFR0100004708JR500	Vishay
1	R7	100	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R8	470	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	22k	Resistor, Chip, 1/16W, 5%	0603	CRCW0603-xxx-J	Vishay
1	R11	169k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R12	10	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R13	61.9k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R15	82k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R16	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	4.75k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std

1	R19	20k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
1	R21	23.7k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R101	33	Resistor, Chip, 1/16W, 5%	0805	Std	Std
2	R14 R20	100k	Resistor, Chip, 1/16W, 1%	0603	CRCW0603-xxxx-F	Vishay
2	R4 R6	3MEG	Resistor, 1/4 watt, 5%	1206	Std	Std
2	R9 R102	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	T1	PA1005.100NL	Transformer, Current Sense, 100:1	0.284 x 0.330 inch	PA1005.100NL	Pulse
1	T2	800uH	Transformer, Flyback	0.840 x 1.150 inch	SP-EFD 20 Rel. 18/08/2011	Kaschke
1	TP1	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
3	TP2-3 TP5	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
1	U1	UCC28610D	IC, Flyback Green-Mode Controller	SO8	UCC28610D	TI
1	U2	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	U3	TL432A	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL432AIDBZR	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
  4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.

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